

Kyocera Ceramic Chip Capacitors are available for different applications as classified below:

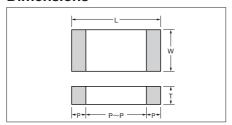
Series	Dielectric Options	Typical Applications	Features	Terminations	Available Size
СМ	COG (NP0) X5R X7R *X6S X7S	General purpose	Wide cap range	Nickel barrier/ Tin	01005, 0201, 0402 0603, 0805, 1206 1210, 1812
СТ	X5R X7R	IC card (Decoupling)	Low profile	Nickel barrier/ Tin	0201, 0402, 0603 0805, 1206, 1210
CU	COG (NP0)	Power amplifier	High-Q	Nickel barrier/ Tin	01005
AT	X5R X7R	Optical communications	Au termination	Nickel barrier/ Au	0201, 0402
ST	X5R X7R X7S	PCB with severe bending conditions	Soft termination	Nickel barrier/ Tin (Soft Termination)	0201, 0402 1206, 1210
CF	COG (NP0) X7R	High voltage & Power circuits	High voltage 250VDC, 630VDC 1000VDC, 2000VDC 3000VDC, 4000VDC	Nickel barrier/ Tin	0805, 1206, 1210 1808, 1812, 2208 2220

<sup>\*</sup> Option

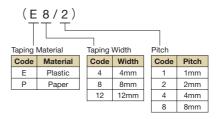
<sup>\*</sup> Negative temperature coefficient dielectric types are available on request.



# **Dimensions**



# %Packaging Code



# **Dimensions and Packaging Quantities**

Size	Co	de	Dimension			Dimensions (m				Maximum quantity per reel			
Size	JIS	EIA	Code	L	W	Т	P min.	P max.	P to P min.	∮180 Reel <sup>®</sup>	∮330 Reel <sup>®</sup>		
02	0402	01005	Α	0.4±0.02	0.2±0.02	0.2±0.02	0.07	0.14	0.13	40kp (E4/1) 20kp (P8/2)	-		
										30kp (P8/1)	150kp (P8/1)		
			Α	0.6±0.03	0.3±0.03	0.22 max.	0.10	0.20	0.20	15kp (P8/2)	50kp (P8/2)		
			В	0.0±0.03	0.5±0.05	0.3±0.03	0.10	0.20	0.20	30kp (P8/1)	150kp (P8/1)		
03	0603	0201								15kp (P8/2) 30kp (P8/1)	50kp (P8/2) 150kp (P8/1)		
	0000	0201	С	0.6±0.05	0.3±0.05	0.3±0.05	0.13	0.23	0.19	15kp (P8/2)	50kp (P8/2)		
			D	0.6±0.09	0.3±0.09	0.3±0.09				15kp (P8/2)	-		
			E F	0.6±0.10	0.3±0.10	0.25 max. 0.3±0.10	0.13	0.23	0.19	15kp (P8/2) 15kp (P8/2)	-		
			Α	0.0=0.10	0.0=0.10	0.22 max.				20kp (P8/1)	100kp (P8/1)		
			Α			U.ZZ IIIdX.	-			10kp (P8/2)	50kp (P8/2)		
			В			0.25 max.				20kp (P8/1) 10kp (P8/2)	100kp (P8/1) 50kp (P8/2)		
			С	1.0±0.05	0.5±0.05	0.33 max.	1			20kp (P8/1)	100kp (P8/1)		
			C	1.0±0.03	0.5±0.05	U.33 IIIdx.	-			10kp (P8/2)	50kp (P8/2)		
			D			0.35 max.				20kp (P8/1) 10kp (P8/2)	100kp (P8/1) 50kp (P8/2)		
			Е			0.5±0.05	1			20kp (P8/1)	100kp (P8/1)		
05	1005	0402	-			0.5±0.05	0.15	0.35	0.30	10kp (P8/2)	50kp (P8/2)		
			F	1.0±0.07	0.5±0.07	0.5±0.07				20kp (P8/1) 10kp (P8/2)	50kp (P8/2)		
			G			0.35 max.	1			20kp (P8/1)	100kp (P8/1)		
			u	1.0±0.10	0.5±0.10	U.UU IIIAX.	-			10kp (P8/2)	50kp (P8/2)		
			Н			0.5±0.10				20kp (P8/1) 10kp (P8/2)	50kp (P8/2)		
			J	1.0±0.15	0.5±0.15	0.5±0.15	1			20kp (P8/1)	50kp (P8/2)		
				1.0±0.15	0.5±0.15					10kp (P8/2)	50KP (P6/2)		
			K L	1.0±0.20	0.5±0.20	0.33 max. 0.5±0.20	-			10kp (P8/2) 10kp (P8/2)	-		
			Ā			0.55 max.				4kp (P8/4)	10kp (P8/4)		
			В	1.6±0.10	0.8±0.10	0.8±0.10	1			8kp (P8/2)	20kp (P8/2)		
					0.8±0.15		-	0.60	0.50	4kp (P8/4) 8kp (P8/2)	10kp (P8/4) 20kp (P8/2)		
405	1000	0000	С	1.010.15		0.55 max.	0.20			4kp (P8/4)	10kp (P8/4)		
105	1608	0603	D	1.6±0.15	0.8±0.15	0.8±0.15	0.20	0.60	0.50	8kp (P8/2)	20kp (P8/2)		
							-			4kp (P8/4) 8kp (P8/2)	10kp (P8/4) 20kp (P8/2)		
			E	1.6±0.20	0.8±0.20	0.55 max.				4kp (P8/4)	10kp (P8/4)		
			F			0.8±0.20	1			*	-		
			A B	2.040.40		0.55 max. 0.95 max.				4kp (P8/4) 4kp (P8/4)	10kp (P8/4) 10kp (P8/4)		
			C			1.00 max.	j			4kp (E8/4)	10kp (E8/4)		
			D	2.0±0.10	2.0±0.10 1.25±0.10	0.6±0.1	]			4kp (P8/4)	10kp (P8/4)		
			E F			0.85±0.10 1.05±0.10	1	0.75		4kp (P8/4) 3kp (E8/4)	10kp (P8/4) 10kp (E8/4)		
21	2012	0805	G			1.25±0.10	0.20		0.70	3kp (E8/4)	10kp (E8/4)		
			H	0.010.45	1051045	0.55 max.				4kp (P8/4)	10kp (P8/4)		
			J K	2.0±0.15	1.25±0.15	0.95 max. 1.25±0.15	1			4kp (P8/4) 3kp (E8/4)	10kp (P8/4) 10kp (E8/4)		
			L	2.0±0.20	1.25±0.20	0.95 max.	]			4kp (P8/4)	10kp (P8/4)		
			M	2.0±0.20	1.23±0.20	1.25±0.20				3kp (E8/4)	10kp (E8/4)		
			A B			0.95 max. 1.00 max.	-			4kp (P8/4) 4kp (E8/4)	10kp (P8/4) 10kp (E8/4)		
			C	3.2±0.20	1.6±0.15	1.15±0.10	j			3kp (E8/4)	10kp (E8/4)		
			D			1.25±0.10	0.30	0.85	1.40	3kp (E8/4)	10kp (E8/4)		
316	3216	1206	E F			1.6±0.15 0.95 max.	-			2.5kp (E8/4) 4kp (P8/4)	5kp (E8/4) 10kp (P8/4)		
			G	3.2±0.20	1.6±0.20	1.00 max.	]			4kp (E8/4)	10kp (E8/4)		
			Н	2 0+0 00		1.6±0.20				2.5kp (E8/4)	5kp (E8/4)		
			J K	3.2±0.30 3.2±0.35	1.6±0.30	1.6±0.30	0.30	0.85	1.90	2kp (E8/4) 2kp (E8/4)	-		
			Α	0.2-0.00		1.00 max.				4kp (E8/4)	10kp (E8/4)		
			В			1.40 max.	-			3kp (E8/4)	10kp (E8/4)		
32	3225	1210	C D	3.2±0.30	2.5±0.20	1.60 max. 1.6±0.15	0.30	1.00	1.40	2.5kp (E8/4) 2.5kp (E8/4)	5kp (E8/4) 5kp (E8/4)		
J.	5220	0	E	0.2_0.00		2.20 max.	] 0.00			2kp (E8/4)	5kp (E8/4)		
			F			2.0±0.2	-			2kp (E8/4)	5kp (E8/4)		
		G A 4 540 20 2 040 20			2.5±0.2 1.6 max.	-			1kp (E8/4) 2kp (E12/4)	4kp (E8/4) -			
42	4520	1808	В	4.5±0.20	2.0±0.20	2.2 max.	0.15	0.85	2.60	2kp (E12/4)	-		
			A	·		2.0 max.				1kp (E12/8)	-		
43	4532	1812	B C	4.5±0.30	3.2±0.20	2.0±0.2 2.5 max.	0.30	1.10	2.00	1kp (E12/8) 0.5kp (E12/8)	-		
-70	7002	1012	D	7.0≟0.00	0.2±0.20	2.5±0.2	0.00	1.10	2.00	0.5kp (E12/8)	-		
	F700	0000	E	5710.10	0.010.00	2.8±0.2	0 :-	0.0=	4.00	0.5kp (E12/8)	-		
52	5720	2208	A	5.7±0.40	2.0±0.20	2.2 max. 2.0 max.	0.15	0.85	4.20	2kp (E12/4) 1kp (E12/8)	-		
55	5750	2220	В	5.7±0.40	5.0±0.40	2.5 max.	0.30	1.40	2.50	0.5kp (E12/8)	-		
			С			2.8 max.				0.5kp (E12/8)	-		
Note: Tar	ina denote	es the quar	ntity packaged r	per reel (kp means	1000 pieces). *	Please contact us.							

Note: Taping denotes the quantity packaged per reel (kp means 1000 pieces). \* Please contact us.



#### **KYOCERA PART NUMBER** CM 03 X5R 225 M 06 Α Н SERIES CODE -General Purpose ΑT Au termination Low Profile ST CT Soft termination CU High-Q CF High Voltage SIZE CODE -SIZE EIA (JIS) SIZE EIA (JIS) 02 = 01005 (0402)32 = 1210 (3225)42 = 1808 (4520) 43 = 1812 (4532) 03 = 0201 (0603) = 0402 (1005) 52 = 2208 (5720) 105 = 0603 (1608)21 = 0805 (2012)55 = 2220 (5750) 316 = 1206 (3216)**DIELECTRIC CODE** -**CODE EIA CODE** CG = C0G (NPO)X7S = X7S (Option) X5R = X5RX6S = X6S (Option)X7R = X7RNegative temperature coefficient dielectric types are available on request. **CAPACITANCE CODE** -Capacitance expressed in pF. Two significant digits plus number of zeros. For Values < 10pF, Letter R denotes decimal point, 100000pF = 1041.5pF = 1R50.1μF = 104 0.5pF = R50100μF 4700pF = 472= 107 **TOLERANCE CODE** - $K = \pm 10\%$ $A = \pm 0.05pF$ (option) $D = \pm 0.5pF$ $B = \pm 0.1 pF$ $G = \pm 2\%$ (option) $M = \pm 20\%$ $C = \pm 0.25 pF$ $J = \pm 5\%$ VOLTAGE CODE — 04 = 4VDC100 = 100VDC1000 = 1000VDC250 = 250VDC2000 = 2000VDC 06 = 6.3VDC10 = 10VDC630 = 630VDC3000 = 3000VDC4000 = 4000VDC16 = 16VDC25 = 25VDC35 = 35VDC50 = 50VDC**TERMINATION CODE** A = Nickel Barrier/Tin \*G = Nickel Barrier/ Au Y = Nickel Barrier/ Cu S = Nickel Barrier/Tin \*K = Nickel Barrier/ Au (Soft Termination) G: AuSn solder and conductive adhesive. K: Wire bonding and conductive adhesive. PACKAGING CODE -B = BulkH = 7" Reel Taping & 2mm Cavity pitch C = Bulk Cassette (option) N = 13" Reel Taping & 2mm Cavity pitch T = 7" Reel Taping & 4mm or 8mm\*1 Cavity pitch W = 13" Reel Taping & 1mm Cavity pitch \*P = 7" Reel Taping & 1mm Cavity pitch Q = 7" Reel Taping & 1mm Cavity pitch L = 13" Reel Taping & 4mm Cavity pitch \* Carrier tape width 4mm. \*1 Applied for size 43 to 55. OPTION -

Thickness max. value is indicated in CT series

EX.  $125 \rightarrow 1.25$ mm max.

095  $\rightarrow$  0.95mm max.



# **Temperature Compensation Type**

Code	ppm	n/ °C	Temperature Range
CG	0	±30	−55 to 125°C
CH	0	±60	-55 to 125 C

Note: All parts of C0G will be marked as "CG" but will conform to the above table.

# **High Dielectric Constant Type**

EIA Dielectric	Temperature Range	∆C max.				
LIA Dielectric	Temperature Hange	AC IIIAX.				
X5R	−55 to 85°C	±15%				
X7R	−55 to 125°C	115%				
X7S	−55 to 125°C	+22%				
*X6S	–55 to 105°C	±2270				

<sup>\*</sup> option

#### **Available Tolerances**

Dielectric materials, capacitance values and tolerances are available in the following combinations only:

EIA Dielectric	Tolerance	Capacitance
	*3 A=±0.05pF	<0.5pF
	B=±0.1pF	≤5pF
	C=±0.25pF	*1 <10pF
COG	D=±0.50pF	ζιορι
	*3 G=±2%	\10 <sub>2</sub> F
	J=±5%	≥10pF E12 Series
	K=±10%	E12 Series
*3 X6S X5R	*2 K=±10%	*4 E3 Series
X7S X7R	M=±20%	E3 Series

#### Note:

#### **E Standard Number**

E3 E6 E12 E24 (Option)  1.0 1.0 1.1  1.10 1.2 1.2 1.3  1.5 1.5 1.6  1.8 1.8 2.0  2.2 2.2 2.4  2.7 2.7 3.0  3.3 3.3 3.3 3.6  3.9 3.9 4.3  4.7 4.7 5.1  5.6 5.6 6.2						
<b>E</b> 3	<b>E</b> 6	E12	E24 (C	ption)		
	1.0	1.0	1.0	1.1		
1.0	1.0	1.2	1.2	1.3		
1.0	1.5	1.5	1.5	1.6		
	1.5	1.8	1.8	2.0		
	2.2	2.2	2.2	2.4		
2.2	2.2	2.7	2.7	3.0		
2.2	2.2	3.3	3.3	3.6		
	3.3	3.9	3.9	4.3		
	4.7	4.7	4.7	5.1		
4.7	4.7	5.6	5.6	6.2		
4.7	6.8	6.8	6.8	7.5		
	0.0	8.2	8.2	9.1		

Temperature coefficients are determined by calculation based on measurement at 20°C and 85°C.

<sup>\*1</sup> Nominal values below 10pF are available in the standard values of 0.5pF, 1.0pF, 1.5pF, 2.0pF, 3.0pF, 4.0pF, 5.0pF, 6.0pF, 7.0pF, 8.0pF, 9.0pF

<sup>\*2</sup> J =  $\pm$ 5% for X7R (X5R) is available on request.

<sup>\*3</sup> option

<sup>\*4</sup> E6 series is available on request.





# [RoHS Compliant Products]

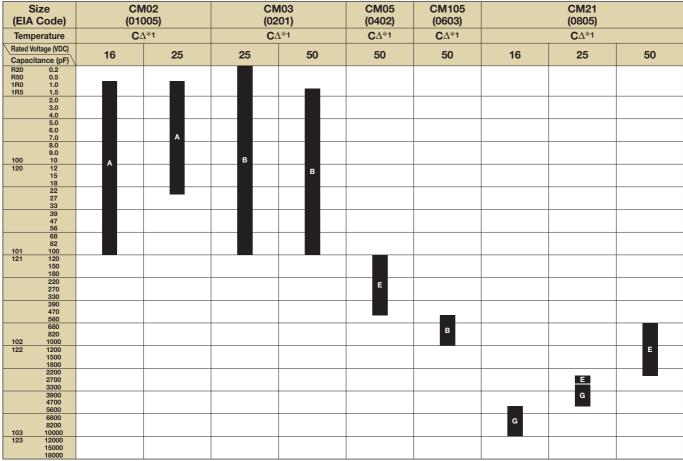
#### **Features**

We offer a diverse product line ranging from ultra-compact (0.4×0.2mm) to large (4.5×3.2mm) components configured for a variety of temperature characteristics, rated voltages, and packages. We offer the choice and flexibility for almost any applications.

# **Applications**

This standard type is ideal for use in a wide range of applications, from commercial to industrial equipment.

# **Temperature Compensation Dielectric**



<sup>&</sup>lt;Standard Capacitance Value>

Please contact for capacitance value other than standard.

Alphabets in capacitance chart denote dimensions. Please refer to the below table for detail.

# (Example)

In case of "B" for CM03; L : 0.6±0.03mm W : 0.3±0.03mm

T: 0.3±0.03mm

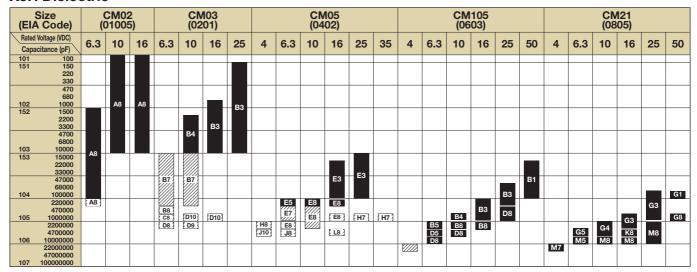
Size	Size	Dimension (mm)								
Size	Code	L	W	Т						
02	Α	0.4±0.02	0.2±0.02	0.2±0.02						
03	В	0.6±0.03	0.3±0.03	0.3±0.03						
05	Е	1.0±0.05	0.5±0.05	0.5±0.05						
105	В	1.6±0.10	0.8±0.10	0.8±0.10						
21	Е	2.0±0.10	1.25±0.10	0.85±0.10						
21	G	2.0±0.10	1.25±0.10	1.25±0.10						





# [RoHS Compliant Products]

#### **X5R Dielectric**



(EIA	Size A Code)				316 06)			CM32 (1210)						CM43 (1812)	
_	Voltage (VDC)	6.3	10	16	25	50	100	4	6.3	10	16	25	50	6.3	50
105	220000 470000 1000000						H3					В3	F1		
106	2200000 4700000 10000000	<b>E</b> 5	E4	E3	E3 H8	H3 ]	2/2/2			F4	C3 G3	F3 G3	G3		D1
107	22000000 4700000 100000000	Н5	Н8	Н8				G5	G5	G4	G3	G8		<b>E</b> 5	

<Standard Capacitance Value>
CM21 size and smaller : E6 Series

CM316 size and larger / capacitance value of 0.1 $\mu$ F and larger : E3 Series Please contact for capacitance value other than standard.

Optional Spec.

Two digits alphanumerics in capacitance chart denote dimensions and tan  $\delta.$  Please refer to the below table for detail.

#### (Example)

In case of "B3" for CM03; L: 0.6±0.03mm W: 0.3±0.03mm T: 0.3±0.03mm

Tan  $\delta$ : 5.0% max.

Size	Size	Dir	mension (m	ım)
Size	Code	L	W	Т
02	Α	0.4±0.02	0.2±0.02	0.2±0.02
	В	0.6±0.03	0.3±0.03	0.3±0.03
03	С	0.6±0.05	0.3±0.05	0.3±0.05
	D	0.6±0.09	0.3±0.09	0.3±0.09
	Е	1.0±0.05	0.5±0.05	0.5±0.05
05	Н	1.0±0.10	0.5±0.10	0.5±0.10
03	J	1.0±0.15	0.5±0.15	0.5±0.15
	L	1.0±0.20	0.5±0.20	0.5±0.20
105	В	1.6±0.10	0.8±0.10	0.8±0.10
105	D	1.6±0.15	0.8±0.15	0.8±0.15
	G	2.0±0.10	1.25±0.10	1.25±0.10
21	K	2.0±0.15	1.25±0.15	1.25±0.15
	M	2.0±0.20	1.25±0.20	1.25±0.20

Size	Size	Dir	nension (m	nm)
Size	Code	L	W	Т
316	Е	3.2±0.20	1.6±0.15	1.6±0.15
310	Н	3.2±0.20	1.6±0.20	1.6±0.20
	В	3.2±0.30	2.5±0.20	1.40 max.
32	С	3.2±0.30	2.5±0.20	1.60 max.
32	F	3.2±0.30	2.5±0.20	2.0±0.2
	G	3.2±0.30	2.5±0.20	2.5±0.2
42	D	4.5±0.30	3.2±0.20	2.5±0.2
43	Е	4.5±0.30	3.2±0.20	2.8±0.2

	$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan δ
	1	2.5% max.
	3	5.0% max.
	4	7.0% max.
	5	7.5% max.
	7	10.0% max.
	8	12.5% max.
	9	15.0% max.
	10	20.0% max.





# [RoHS Compliant Products]

#### X7R Dielectric

	Size A Code)	CM02 (01005)		CM03 (0201)		CN (04				CM105 (0603)					CM21 (0805)		
	Voltage (VDC) citance (pF)	16	10	16	25	16	25	6.3	10	16	25	50	6.3	10	16	25	50
101 151	100 150 220 330			B2	B2												
102 152	470 680 1000 1500	A8		62													
132	2200 3300 4700		В3														
103 153	6800 10000 15000 22000					E2	E3										
104	33000 47000 68000 100000					E8	E8			B2	B2	B1					G1
105	220000 470000 1000000								B3 B8	В8	D8			G3	G2 G8	G2 G8	M3
106	2200000 4700000 10000000 22000000							D8					M8	M8 (M8)	M8	M8	

Size (EIA Code)	CM316 (1206)				CM32 (1210)					143 12)			
Rated Voltage (VDC)  Capacitance (pF)	6.3	10	16	25	50	100	10	16	25	50	100	50	100
47000 104 100000						C1 E1							
220000 470000 105 1000000			C2	E2		EI			B2	B1 F1	G1	B1	D1
2200000 470000 106 1000000 2200000	H8	E3 H8 H5	Н8	H8 H3	[H3]		G8	G2 G8	G8	G3		D1	

Optional Spec.

<Standard Capacitance Value>

Size

21

CM21 size and smaller : E6 Series

CM316 size and larger / capacitance value of  $0.1\mu F$  and larger : E3 Series

Dimension (mm)

Please contact for capacitance value other than standard.

Two digits alphanumerics in capacitance chart denote dimensions and  $\tan \delta$ . Please refer to the below table for detail.

#### (Example)

(Example)
In case of "B3" for CM03;
L: 0.6±0.03mm
W: 0.3±0.03mm
T: 0.3±0.03mm Tan  $\delta$ : 5.0% max.

	Size	Code	L	W	Т				
	02	Α	0.4±0.02	0.2±0.02	0.2±0.02				
	03	В	0.6±0.03	0.3±0.03	0.3±0.03				
	05	E	1.0±0.05	0.5±0.05	0.5±0.05				
	105	В	1.6±0.10	0.8±0.10	0.8±0.10				
		D	1.6±0.15	0.8±0.15	0.8±0.15				
	04	G	2.0±0.10	1.25±0.10	1.25±0.10				

Size	Size	Dimension (mm)					
Size	Code	L	W	Т			
	С	3.2±0.20	1.6±0.15	1.15±0.10			
316	E	3.2±0.20	1.6±0.15	1.6±0.15			
	Н	3.2±0.20	1.6±0.20	1.6±0.20			
	В	3.2±0.30	2.5±0.20	1.40 max.			
32	F	3.2±0.30	2.5±0.20	2.0±0.2			
	G	3.2±0.30	2.5±0.20	2.5±0.2			
40	В	4.5±0.30	3.2±0.20	2.0±0.2			
43	D	4.5±0.30	3.2±0.20	2.5±0.2			

Tan δ Code	Tan δ
1	2.5% max.
2	3.5% max.
3	5.0% max.
5	7.5% max.
8	12.5% max.

#### X7S Dielectric

ATO BIOLOGIA IO					
Size (EIA Code)	CM316 (1206)				
Rated Voltage (VDC)  Capacitance (pF)	100				
47000 104 100000					
220000 470000 105 1000000					
2200000 4700000 106 10000000 22000000	⊠ H3 ⊠ ☑ J3 ☑				

Size	Size Code	Dimension (mm)					
Size	Code	L	W	Т			
316	Н	3.2±0.20	1.6±0.20	1.6±0.20			
	J	3.2±0.30	1.6±0.30	1.6±0.30			

2.0±0.20 | 1.25±0.20 | 1.25±0.20

$\begin{array}{c} \text{Tan } \delta \\ \text{Code} \end{array}$	Tan δ
3	5.0% max.

Two digits alphanumerics in capacitance chart denote dimensions and tan  $\delta. \,$ Please refer to the below table for detail.

Optional Spec.



# Test Conditions and Specifications for Temperature Compensation Type (C△ Characteristics) CM/ CU/ CF Series

Test	Items		Test Condition	ns	Specifications	
Capacitance V	/alue (C)	Capacitano	e Frequency	Volt	Within tolerance	
Q		C≤1000pF C>1000pF		0.5 to 5Vrms	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
Insulation Res	Insulation Resistance (IR)		the rated voltage ambient. oltage of over 630 room ambient. d discharge curreled 50mA.		Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less	
Dielectric Res	istance	Apply 3 times of the rated voltage for 1 to 5 seconds. Apply 1.5 times when the rated voltage is 250V or over. Apply 1.2 times when the rated voltage is 630V or over. The charge and discharge current of the capacitor must not exceed 50mA.			No problem observed	
Appearance		Microscope			No problem observed	
Termination St	trength		ord force of 500g le. Apply 2N for 0	` '	No problem observed	
Bending Stren	gth	Glass epoxy PC time 10 second		ng: 90mm, duration	No significant damage at 1mm bent	
Vibration	Appearance		ency: 10 to 55 (H	z)	No problem observed	
Test	ΔC	Amplitude: 1.5 Sweeping cond		OHz/ 1 minute in X,	Within Tolerance	
	Q	Y and Z	ours each, 6 hour		C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
Soldering	Appearance	Soak the samp	le in 260°C±5°C	solder for 10±0.5	No problem observed	
Heat Resistance	ΔC	seconds and p after 24±2 hou		ient, and measure	Within ±2.5% or ±0.25pF, whichever is larger	
nesistance	Q	(Pre-heating conditions)			C≥30pF : Q≥1000	
		Order	Temperature Time		C<30pF: Q≥400+20C	
	IR	2	80 to 100°C 150 to 200°C	2 minutes	Over $10000M\Omega$ or $500M\Omega$ • $\mu\text{F}$ whichever is less	
	Withstanding Voltage	2 150 to 200°C 2 minutes  The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.			Resist without problem	
Solderablity		Sn-3Ag-0.5Cu         245±5°C         3±0.5 sec.           Sn63 Solder         235±5°C         2±0.5 sec.			Solder coverage : 90% min.	
Temperature	Appearance	(Cycle)			No problem observed	
Cycle	ΔC	Room tempera	ture (3min.)→		Within ±2.5% or ±0.25pF, whichever is larger	
	Q	Lowest operati Room tempera	on temperature (3 ture (3 min.) $\rightarrow$	,	C≥30pF: Q≥1000 C<30pF: Q≥400+20C	
	IR	Highest operat	ion temperature(3	30min.)	Over $10000M\Omega$ or $500M\Omega$ • $\mu\text{F}$ , whichever is less	
	Withstanding Voltage  After 5 cycles, measure after 24±2 hours.  The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.		Resist without problem			
Load	Appearance			500+12/ -0 hours	No problem observed	
Humidity Test	ΔC		n at 40°C±2°C, hu	umidity 90 to for 24±2 hours, at	Within ±7.5% or ±0.75pF, whichever is larger	
(Except CF Series)	Q	room temperat	ure before meası		C≥30pF: Q≥200 C<30pF: Q≥100+10C/3	
	IR	_	ed 50mA for IR m		Over 500M $\Omega$ or 25M $\Omega$ • $\mu$ F, whichever is less	
High-	Appearance	After applying	wice the rated vo	oltage at the	No problem observed.	
Temperature	ΔC		125±3°C for 100		Within ±3% or ±0.3pF, whichever is larger	
with Loading	Q	Apply 1.5 times Apply 1.2 times	when the rated volt	hours. age is 250V or over. age is 630V or over. nt of the capacitor	C≥30pF: Q≥350 10pF <c<30pf: 2<br="" q≥275+5c="">C&lt;10pF: Q≥200+10C</c<30pf:>	
	IR	must not excee	ed 50mA for IR m	easurement.	Over 1000M $\Omega$ or 50M $\Omega$ • $\mu$ F, whichever is less	

Please ask for individual specification for the hatched range in previous chart.



# Test Conditions and Specifications for High Dielectric Type (X5R, X7R) CM/ CT Series

Test Items		Test Conditions	Specifications	
Capacitance V	/alue (C)	Measure after heat treatment	Within tolerance	
Tanδ (%)			Refer to capacitance chart	
Insulation Res	sistance (IR)	Measured after the rated voltage is applied for 1 minute at room ambient. The charge and discharge current of the capacitor must not exceed 50mA.	Over 10000M $\Omega$ or 500M $\Omega$ • $\mu$ F, whichever is less	
Dielectric Res	istance	Apply 2.5 times of the rated voltage for 1 to 5 seconds. The charge and discharge current of the capacitor must not exceed 50mA.	No problem observed	
Appearance		Microscope	No problem observed	
Termination S	trength	Apply a sideward force of 500g (5N) to a PCB-mounted sample. note: 2N for 0201 size in for 01005 size. Exclude CT series with thickness of less than 0.66mm.	No problem observed	
Bending Stren	gth	Glass epoxy PCB: Fulcrum spacing: 90mm, duration time 10 seconds. Exclude CT series with thickness of less than 0.66mm.	No significant damage at 1mm bent	
Vibration	Appearance	Take the initial value after heat treatment.	No problem observed	
Test	ΔC	Vibration frequency: 10 to 55 (Hz)  Amplitude: 1.5mm	Within tolerance	
	Tanδ (%)	Sweping condition: 10→55→10Hz/ 1 minute in X, Y and Z Directions: 2 hours each, 6 hours total.	Within tolerance	
Soldering	Appearance	Take the initial value after heat treatment.  Soak the sample in 260°C±5°C solder for 10±0.5	No problem observed	
Heat Resistance	ΔC	seconds and place in room ambient, and measure	Within ±7.5%	
nesistance	Tanδ (%)	after 24±2 hours.	Within tolerance	
	IR	(Pre-heating conditions)	Over $10000M\Omega$ or $500M\Omega$ • $\mu\text{F}$ , whichever is less	
	Withstanding Voltage	Order         Temperature         Time           1         80 to 100°C         2 minutes           2         150 to 200°C         2 minutes   The charge and discharge current of the capacitor must not	Resist without problem	
Solderablity		exceed 50mA for IR and withstanding voltage measurement.           Soaking condition         Sn-3Ag-0.5Cu         245±5°C         3±0.5 sec.           Sn63 Solder         235±5°C         2±0.5 sec.	Solder coverage : 90% min.	
Temperature	Appearance	Take the initial value after heat treatment. (Cvcle)	No problem observed	
Cycle	Δ <b>C</b>	Room temperature (3min.)→	Within ±7.5%	
	Tanδ (%)	Lowest operation temperature (30min.)→	Within tolerance	
	IR	Room temperature (3min.) →	Over 10000MΩ or 500MΩ • μF, whichever is less	
	Withstanding Voltage  Highest operation temperature(30min.)  After 5 cycles, measure after 24±2 hours. The charge and discharge current of the capacitor must not exceed 50mA for IR and withstanding voltage measurement.		Resist without problem	
Load	Appearance	Take the initial value after voltage treatment.	No problem observed	
Humidity Test	ΔC	After applying rated voltage for 500+12/ –0 hours in pre-condition at 40°C±2°C, humidity 90 to	Within ±12.5%	
iest	Tanδ (%)	95%RH, allow parts to stabilize for 24±2 hours, at	200% max. of initial value	
	IR	room temperature before measurement. The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.	Over $500 M\Omega$ or $25 M\Omega$ • $\mu F$ , whichever is less	
High-	Appearance	Take the initial value after voltage treatment.	No problem observed	
Temperature	ΔC	After applying twice the rated voltage at the highest operation temperature for 1000+12/ –0 hours,	Within ±12.5%	
with	Tanδ (%)	measure the sample after 24±2 hours.	200% max. of initial value	
The charge and d must not exceed Apply 1.5 times when the		The charge and discharge current of the capacitor must not exceed 50mA for IR measurement.  Apply 1.5 times when the rated voltage is 10V or less. Applied voltages for respective products are indicated in the below chart.	Over 1000M $\Omega$ or 50M $\Omega$ • $\mu$ F, whichever is less	

Pre-treat-	Heat	Keep specimen at 150+0/ −10°C for 1 hour, leave specimen at room ambient for 24±2 hours.
ment	Voltage	Apply the same test condition for 1 hour, then leave the specimen at room ambient for 24±2 hours.

High-temperature with Loading Applied Voltage (Rated Voltage  $\times\,\square$  )

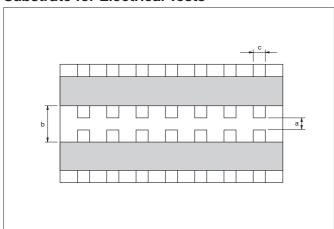
Applied Voltage	Rated Voltage	Products
	4V	CT03X5R104
×1.3	6.3V	CM105X5R475, CM316X5R476, CM02X5R153-104
	0.5 V	CT05X5R104, CT21X5R106, CT03X5R104
	16V	CM02X7R101-222, CM05X7R333-104, CM105X7R474-105, CM21X7R105-475, CM316X7R475-106, CM32X7R106-226, CM05X5R224, CM105X5R225, CM21X5R475-106, CM316X5R226
	100	CT105X5R105, CT21X5R225-475, CT316X5R106, CM03X5R332-103, CM02X5R101-103
	25V	CM105X7R474, CM21X7R105-225, CM316X7R475, CM32X7R106, CM105X5R474-105, CM21X5R225-106, CM316X5R106, CM32X5R106-226
×1.5	250	CT316X5R225-106, CM03X5R152-103, CM05X7R103-104
	50V	CM21X5R105, CM32X5R106, CM32X7R106
	500	CT21X5R225, CT316X5R105-475
	100V	CM32X7RK74, CM43X7R105

Please ask for individual specification for the hatched range in previous chart.



(Unit: mm)

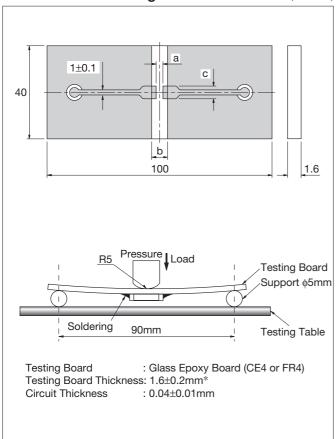
# **Substrate for Electrical Tests**



Size (EIA Code)	а	b	С
02 (01005)	0.15	0.50	0.20
03 (0201)	0.26	0.92	0.32
05 (0402)	0.4	1.4	0.5
105 (0603)	1.0	3.0	1.2
21 (0805)	1.2	4.0	1.65
316 (1206)	2.2	5.0	2.0
32 (1210)	2.2	5.0	2.9
42 (1808)	3.5	7.0	3.7
43 (1812)	3.5	7.0	3.7
52 (2208)	4.5	8.0	5.6
55 (2220)	4.5	8.0	5.6

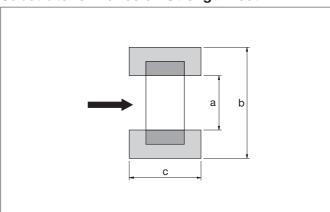
# **Substrate for Bending Test**





#### \* 02, 03, 05 size 0.8±0.1mm

# **Substrate for Adhesion Strength Test**

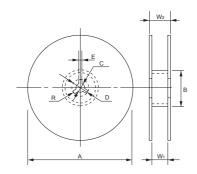




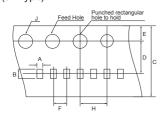


# **Tape and Reel**

• Reel

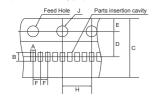


# F=1mm (02 Type)



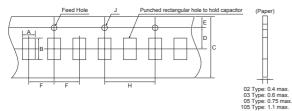


F=1mm (02, 03, 05 Type)

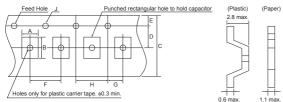




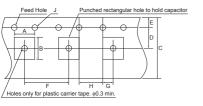
F=2mm (02, 03, 05, 105 Type)

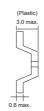


# F=4mm (105, 21, 316, 32, 42, 52 Type)



# F=8mm (43, 55 Type)





# Reel

(Unit: mm)

Code Reel	Α	В	С	D
7-inch Reel (CODE: T, H, Q)	180 +0 -2.0			
7-inch Reel (CODE: P)	178±2.0	φ60 min.	13±0.5	21±0.8
13-inch Reel (CODE: L, N, W)	330±2.0			
Code Reel	E	<b>W</b> 1	<b>W</b> 2	R
	E	<b>W</b> <sub>1</sub>	<b>W</b> <sub>2</sub> 16.5 max.	R
Reel 7-inch Reel	<b>E</b> 2.0±0.5			<b>R</b>

<sup>\*</sup> Carrier tape width 8mm.

#### **Carrier Tape**

(Unit: mm)

Carrier Tape (OIII			
Size (EIA Code)	Α	В	F
02 (01005)*	0.23±0.02	0.43±0.02	1.0±0.02
02 (01003)	0.25±0.03	0.45±0.03	2.0±0.05
03 (0201)*	0.0710.00	0.67±0.03	1.0±0.05
	0.37±0.03		2.0±0.05
05 (0402)*	0.65±0.1	1.15±0.1	1.0±0.05
			2.0±0.05
105 (0603)	1.0±0.2	1.8±0.2	4.0±0.1
21 (0805)	1.5±0.2	2.3±0.2	4.0±0.1
316 (1206)	2.0±0.2	3.6±0.2	4.0±0.1
32 (1210)	2.9±0.2	3.6±0.2	4.0±0.1
42 (1808)	2.4±0.2	4.9±0.2	4.0±0.1
43 (1812)	3.6±0.2	4.9±0.2	8.0±0.1
52 (2208)	2.4±0.2	6.0±0.2	4.0±0.1
55 (2220)	5.3±0.2	6.0±0.2	8.0±0.1

<sup>\*</sup> Option

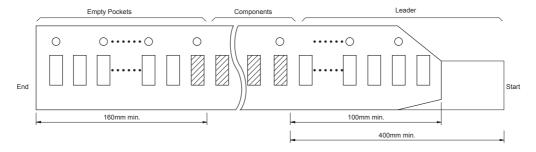
(Unit: mm)

F	Carrier Tape	С	D	E	G	Н	J
1.0	4mm	4.0	1.8	0.9	_	2.0	8.0
±0.02	Plastic	+0.08	±0.02	±0.05		±0.04	±0.04
1.0		8.0				4.0	
±0.05		+0.3/ -0.1				±0.05	
2.0 ±0.05	8mm Paper		3.5				
		8.0 ±0.3	±0.05	1.75	2.0		1.5
4.0	8mm			±0.1	±0.05	4.0	+0.1/ -0
±0.1	Plastic					±0.1	
	12mm	12.0	5.5				
8.0 ±0.1	Plastic	±0.3	±0.05				

For size 42 (1808) or over, Tape width 12mm and W1: 14±1.5, W2: 18.4mm max.



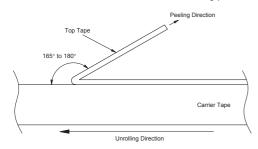
#### **Detail of leader and trailer**

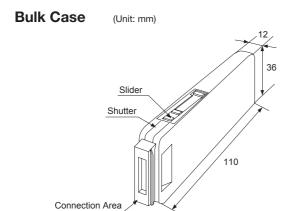


# Adhesive tape

- 1) The exfoliative strength when peeling off the top tape from the carrier tape by the method of the following figure shall be  $^{\circ}0.1$  to 0.7N.\*02 Size: 0.1 to 0.5N
- 2) When the top tape is peeled off, the adhesive stays on the top tape.
- 3) Chip capacitors will be in a state free without being stuck on the thermal adhesive tape.

Exfoliating angle: 165 to 180 degrees to the carrier tape Exfoliating speed: 300 mm/min.





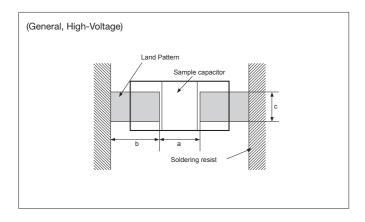
• Please contact Kyocera for details.



# **Dimensions for recommended typical land**

Since the amount of solder (size of fillet) to be used has direct influence on the capacitor after mounting, the sufficient consideration is necessary.

When the amounts of solder is too much, the stress that a capacitor receives becomes larger. It may become the cause of a crack in the capacitor. When the land design of printed wiring board is considered, it is necessary to set up the form and size of land pattern so that the amount of solder is suitable.



# General, High-Voltage

(Unit: mm)

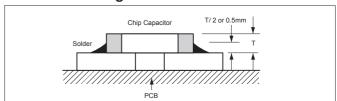
Size (EIA Code)	L×W	а	b	С
02 (01005)	0.4×0.2	0.13 to 0.20	0.12 to 0.18	0.20 to 0.23
03 (0201)	0.6×0.3	0.20 to 0.30	0.25 to 0.35	0.30 to 0.40
05 (0402)	1.0×0.5	0.30 to 0.50	0.35 to 0.45	0.40 to 0.60
105 (0603)	1.6×0.8	0.70 to 1.00	0.80 to 1.00	0.60 to 0.80
21 (0805)	2.0×1.25	1.00 to 1.30	1.00 to 1.20	0.80 to 1.10
316 (1206)	3.2×1.6	2.10 to 2.50	1.10 to 1.30	1.00 to 1.30
32 (1210)	3.2×2.5	2.10 to 2.50	1.10 to 1.30	1.90 to 2.30
42 (1808)	4.5×2.0	2.50 to 3.20*1	1.80 to 2.30	1.50 to 1.80
43 (1812)	4.5×3.2	2.50 to 3.20*1	1.80 to 2.30	2.60 to 3.00
52 (2208)	5.7×2.0	4.20 to 4.70	2.00 to 2.50	1.50 to 1.80
55 (2220)	5.7×5.0	4.20 to 4.70	2.00 to 2.50	4.20 to 4.70

<sup>\*1</sup> Dimension of 3.0 to 3.5mm is recommended for "a", in the case of High-Voltage products.

# **Design of printed circuit and Soldering**

The recommended fillet height shall be 1/2 of the thickness of capacitors or 0.5mm. When mounting two or more capacitors in the common land, it is necessary to separate the land with the solder resist strike so that it may become the exclusive land of each capacitor.

# **Ideal Solder Height**



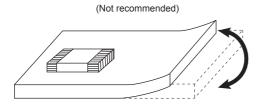
Item	Not recommended example	Recommended example/ Separated by solder
Multiple parts mount		Solder resist
Mount with leaded parts	Leaded parts	Solder resist  Leaded parts
Wire soldering after mounting	Soldering iron Wire	Solder resist
Overview	Solder resist	Solder resist

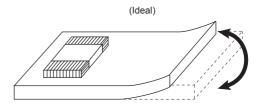


# **Mounting Design**

The chip could crack if the PCB warps during processing after the chip has been soldered.

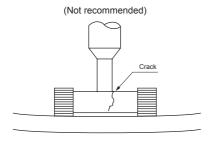
# Recommended chip position on PCB to minimize stress from PCB warpage

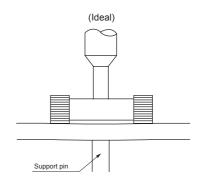




#### **Actual Mounting**

- 1) If the position of the vacuum nozzle is too low, a large force may be applied to the chip capacitor during mounting, resulting in cracking.
- 2) During mounting, set the nozzle pressure to a static load of 1 to 3 N.
- 3) To minimize the shock of the vaccum nozzle, provide a support pin on the back of the PCB to minimize PCB flexture.





- 4) Bottom position of pick up nozzle should be adjusted to the top surface of a substrate which camber is corrected.
- 5) To reduce the possibility of chipping and cracks, minimize vibration to chips stored in a bulk case.
- 6) The discharge pressure must be adjusted to the part size. Verify the pressure during setup to avoid fracturing or cracking the chips capacitors.

### **Resin Mold**

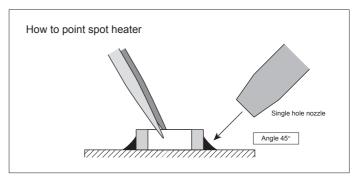
- 1) If a large amount of resin is used for molding the chip, cracks may occur due to contraction stress during curing. To avoid such cracks, use a low shrinkage resin.
- 2) The insulation resistance of the chip will degrade due to moisture absorption. Use a low moisture absorption resin.
- 3) Check carefully that the resin does not generate a decomposition gas or reaction gas during the curing process or during normal storage. Such gases may crack the chip capacitor or damage the device itself.

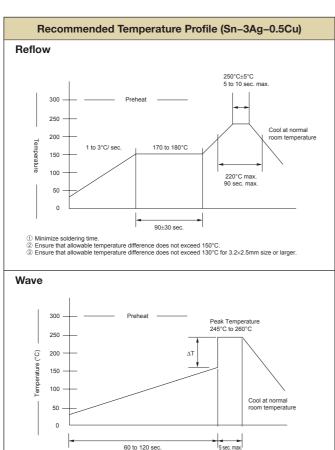


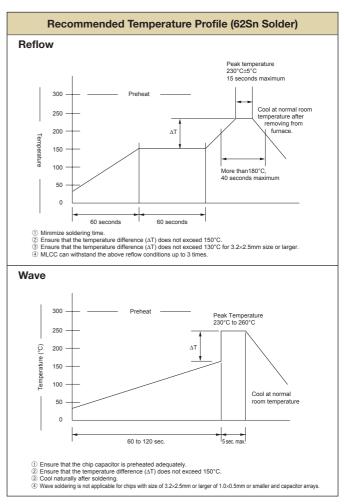
#### **Soldering Method**

- 1) Ceramic is easily damaged by rapid heating or cooling. If some heat shock is unavoidable, preheat enough to limit the temperature difference (Delta T) to within 150 degree Celsius.
- 2) The product size 1.6×0.8mm to 3.2×1.6mm can be used in reflow and wave soldering, and the product size of bigger than 3.2×1.6mm, or smaller than 1.6×0.8mm can be used in reflow.
  - Circuit shortage and smoking can be created by using capacitors which are used neglecting the above caution.
- 3) Please see our recommended soldering conditions.
- 4) In case of using Sn-Zn Solder, please contact us in advance.
- 5) The following condition is recommended for spot heater application.
- · Recommended spot heater condition

Item	Condition
Distance	5mm min.
Angle	45°
Projection Temp.	400°C max.
Flow rate	Set at the minimum
Nozzle diameter	2φ to 4φ (Single hole type)
Application time	10 sec. max. (1206 and smaller) 30 sec.max. (1210 and larger)







#### Soldering iron

1) Temperature of iron chip 1206 and smaller 350°C max. 5) Cautions

1210 and larger 280°C max.

80W max. 2) Wattage

① Ensure that the chip capacitor is preheated adequately. ② Ensure that the temperature difference ( $\Delta T$ ) does not exceed 150°C.

3) Tip shape of soldering iron \$3.0mm max.

Cool naturally after soldering.
 Wave soldering is not applicable for chips with size of 3.2×2.5mm or larger of 1.0×0.5mm or smaller and capacitor arrays

4) Soldering Time

3 sec. max.

a) Pre-heating is necessary rapid heating must be avoided.

Delta T≤150°C (product size of bigger than 3.2×1.6mm. Delta T≤130°C)

- b) Avoid direct touching to capacitors.
- c) Avoid rapid cooling after soldering. Natural cooling is recommended.
- \*Consult as if it is difficult to keep the temperature 280°C max. for 1210 and larger MLCC'S.



# **Circuit Design**

- 1. Once application and assembly environments have been checked, the capacitor may be used in conformance with the rating and performance which are provided in both the catalog and the specifications. Use exceeding that which is specified may result in inferior performance or cause a short, open, smoking, or flaming to occur, etc.
- 2. Please consult the manufacturer in advance when the capacitor is used in devices such as: devices which deal with human life, i.e. medical devices; devices which are highly public orientated; and devices which demand a high standard of liability.
  Accident or malfunction of devices such as medical devices, space equipment and devices having to do with atomic power could generate grave consequence with respect to human lives or, possibly, a portion of the public. Capacitors used in these devices may require high reliability design different from that of general purpose capacitors.
- 3. Please use the capacitors in conformance with the operating temperature provided in both the catalog and the specifications.

  Be especially cautious not to exceed the maximum temperature. In the situation the maximum temperature set forth in both the catalog and specifications is exceeded, the capacitor's insulation resistance may deteriorate, power may suddenly surge and short-circuit may occur.

  The capacitor has a loss, and may self-heat due to equivalent series resistance when alternating electric current is passed therethrough. As this effect becomes especially pronounced in high frequency circuits, please exercise caution.

  When using the capacitor in a (self-heating) circuit, please make sure the surface of the capacitor remains under the maximum temperature for usage. Also, please make certain temperature rises remain below 20°C.
- 4. Please keep voltage under the rated voltage which is applied to the capacitor. Also, please make certain the peak voltage remains below the rated voltage when AC voltage is super-imposed to the DC voltage.
  In the situation where AC or pulse voltage is employed, ensure average peak voltage does not exceed the rated voltage.
  Exceeding the rated voltage provided in both catalog and specifications may lead to defective withstanding voltage or, in worst case situations, may cause the capacitor to smoke or flame.
- 5. When the capacitor is to be employed in a circuit in which there is continuous application of a high frequency voltage or a steep pulse voltage, even though it is within the rated voltage, please inquire to the manufacturer.
  In the situation the capacitor is to be employed using a high frequency AC voltage or a extremely fast rising pulse voltage, even though it is within the rated voltage, it is possible capacitor reliability will deteriorate.
- 6. It is a common phenomenon of high-dielectric products to have a deteriorated amount of static electricity due to the application of DC voltage.

  Due caution is necessary as the degree of deterioration varies depending on the quality of capacitor materials, capacity, as well as the load voltage at the time of operation.
- 7. Do not use the capacitor in an environment where it might easily exceed the respective provisions concerning shock and vibration specified in the catalog and specifications.
  In addition, it is a common piezo phenomenon of high dielectric products to have some voltage due to vibration or to have noise due to voltage change. Please contact sales in such case.
- 8. If the electrostatic capacity value of the delivered capacitor is within the specified tolerance, please consider this when designing the respective product in order that the assembled product function appropriately.
- 9. Please contact us upon using conductive adhesives.

#### **Storage**

- 1. If the component is stored in minimal packaging (a heat–sealed or zippered plastic bag), the bag should be kept closed. Once the bag has been opened, reseal it or store it in a desiccator.
- $2. \ Keep\ storage\ place\ temperature\ + 5\ to\ + 40\ degree\ C,\ humidity\ 20\ to\ 70\%\ RH.\ See\ JIS\ C\ 60721-3-1,\ class\ 1K2\ for\ other\ climatic\ conditions.$
- 3. The storage atmosphere must be free of corrosive gas such as sulfur dioxide and chlorine. Also, avoid exposing the product to saline moisture. If the product is exposed to such atmospheres, the terminals will oxidize and solderability will be effected.
- 4. Precautions 1) to 3) apply to chip capacitors packaged in carrier tapes and bulk cases.
- 5. The solderability is assured for 6 months from our shipping date if the above storage precautions are followed.
- 6. Chip capacitors may crack if exposed to hydrogen (H2) gas while sealed or if coated with silicon, which generates hydrogen gas.

Safety application guideline and detailed information of electrical properties are also provided in Kyocera home page; URL: http://www.kyocera.co.jp/electronic/